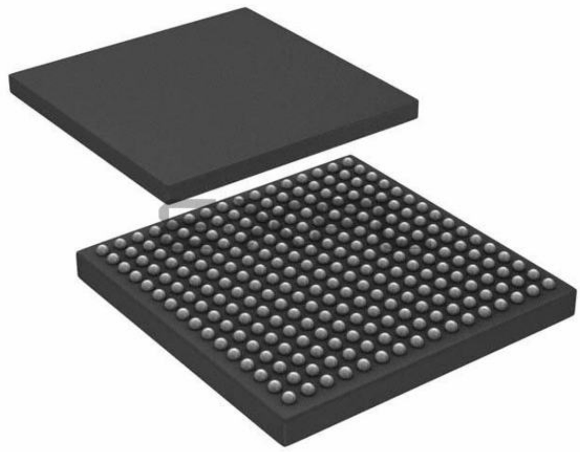

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Active
Number of LABs/CLBs	4224
Number of Logic Elements/Cells	-
Total RAM Bits	55296
Number of I/O	138
Number of Gates	250000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-55°C ~ 125°C (TA)
Package / Case	256-LBGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ax250-1fg256m

Two C-cells, a single R-cell, two Transmit (TX), and two Receive (RX) routing buffers form a Cluster, while two Clusters comprise a SuperCluster (Figure 1-4). Each SuperCluster also contains an independent Buffer (B) module, which supports buffer insertion on high-fanout nets by the place-and-route tool, minimizing system delays while improving logic utilization.

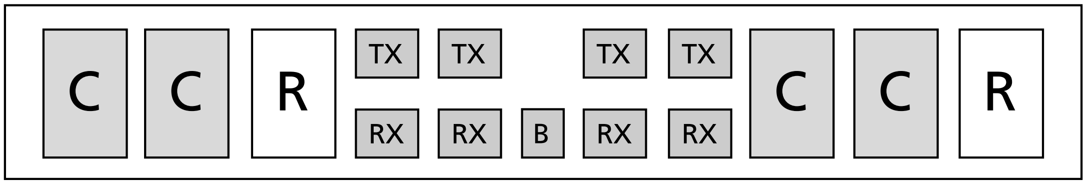


Figure 1-4 • **AX SuperCluster**

The logic modules within the SuperCluster are arranged so that two combinatorial modules are side-by-side, giving a C–C–R – C–C–R pattern to the SuperCluster. This C–C–R pattern enables efficient implementation (minimum delay) of two-bit carry logic for improved arithmetic performance (Figure 1-5 on page 1-3).

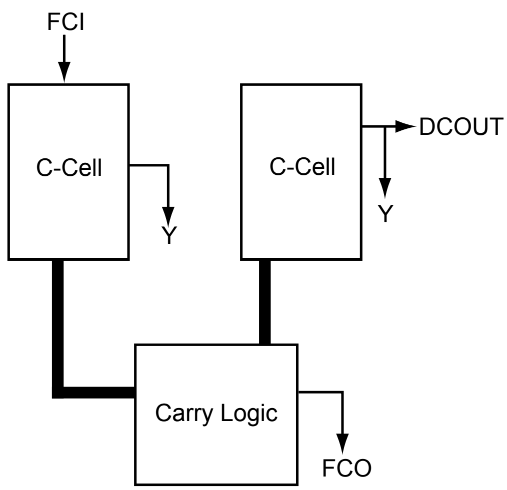


Figure 1-5 • **AX 2-Bit Carry Logic**

The AX architecture is fully fracturable, meaning that if one or more of the logic modules in a SuperCluster are used by a particular signal path, the other logic modules are still available for use by other paths.

At the chip level, SuperClusters are organized into core tiles, which are arrayed to build up the full chip. For example, the AX1000 is composed of a 3x3 array of nine core tiles. Surrounding the array of core tiles are blocks of I/O Clusters and the I/O bank ring (Table 1-1). Each core tile consists of an array of 336 SuperClusters and four SRAM blocks (176 SuperClusters and three SRAM blocks for the AX250).

Table 1-1 • **Number of Core Tiles per Device**

Device	Number of Core Tiles
AX125	1 regular tile
AX250	4 smaller tiles
AX500	4 regular tiles
AX1000	9 regular tiles
AX2000	16 regular tiles

User I/Os[2]

Introduction

The Axcelerator family features a flexible I/O structure, supporting a range of mixed voltages (1.5 V, 1.8 V, 2.5 V, and 3.3 V) with its bank-selectable I/Os. Table 2-8 on page 2-12 contains the I/O standards supported by the Axcelerator family, and Table 2-10 on page 2-12 compares the features of the different I/O standards.

Each I/O provides programmable slew rates, drive strengths, and weak pull-up and weak pull-down circuits. The slew rate setting is effective for both rising and falling edges.

I/O standards, except 3.3 V PCI and 3.3 V PCI-X, are capable of hot insertion. 3.3 V PCI and 3.3 V PCI-X are 5 V tolerant with the aid of an external resistor.

The input buffer has an optional user-configurable delay element. The element can reduce or eliminate the hold time requirement for input signals registered within the I/O cell. The value for the delay is set on a bank-wide basis. Note that the delay WILL be a function of process variations as well as temperature and voltage changes.

Each I/O includes three registers: an input (InReg), an output (OutReg), and an enable register (EnReg). I/Os are organized into banks, and there are eight banks per device—two per side (Figure 2-6 on page 2-18). Each I/O bank has a common VCCI, the supply voltage for its I/Os.

For voltage-referenced I/Os, each bank also has a common reference-voltage bus, VREF. While VREF must have a common voltage for an entire I/O bank, its location is user-selectable. In other words, any user I/O in the bank can be selected to be a VREF.

The location of the VREF pin should be selected according to the following rules:

- Any pin that is assigned as a VREF can control a maximum of eight user I/O pad locations in each direction (16 total maximum) within the same I/O bank.
- I/O pad locations listed as no connects are counted as part of the 16 maximum. In many cases, this leads to fewer than eight user I/O package pins in each direction being controlled by a VREF pin.
- Dedicated I/O pins such as GND and VCCI are counted as part of the 16.
- The two user I/O pads immediately adjacent on each side of the VREF pin (four in total) may only be used as inputs. The exception is when there is a VCCI/GND pair separating the VREF pin and the user I/O pad location.
- The user does not need to assign VREF pins for OUTBUF and TRIBUF. VREF pins are needed only for input and bidirectional I/Os.

The differential amplifier supply voltage VCCDA should be connected to 3.3 V.

A user can gain access to the various I/O standards in three ways:

- Instantiate specific library macros that represent the desired specific standard.
- Use generic I/O macros and then use Designer's PinEditor to specify the desired I/O standards (please note that this is not applicable to differential standards).
- A combination of the first two methods.

Refer to the *I/O Features in Axcelerator Family Devices* application note and the *Antifuse Macro Library Guide* for more details.

2. *Do not use an external resister to pull the I/O above V_{CCI} for a higher logic "1" voltage level. The desired higher logic "1" voltage level will be degraded due to a small I/O current, which exists when the I/O is pulled up above V_{CCI}.*

Table 2-13 summarizes the different combinations of voltages and I/O standards that can be used together in the same I/O bank.

Table 2-13 **• Legal I/O Usage Matrix**

I/O Standard	LVTTL 3.3 V	LVCMOS 2.5 V	LVCMOS1.8 V	LVCMOS1.5 V (JESD8-11)	3.3V PCI/PCI-X	GTL + (3.3 V)	GTL + (2.5 V)	HSTL Class I (1. 5V)	SSTL2 Class I & II (2.5 V)	SSTL3 Class I & II (3.3 V)	LVDS (2.5 V)	LVPECL (3.3 V)
LVTTL 3.3 V (VREF=1.0 V)	✓	–	–	–	✓	✓	–	–	–	–	–	✓
LVTTL 3.3 V(VREF=1.5 V)	✓	–	–	–	✓	–	–	–	–	✓	–	✓
LVCMOS 2.5 V (VREF=1.0 V)	–	✓	–	–	–	–	✓	–	–	–	✓	–
LVCMOS 2.5 V (VREF=1.25V)	–	✓	–	–	–	–	–	–	✓	–	✓	–
LVCMOS1.8 V	–	–	✓	–	–	–	–	–	–	–	–	–
LVCMOS1.5 V (VREF = 1.75 V) (JESD8-11)	–	–	–	✓	–	–	–	✓	–	–	–	–
3.3 V PCI/PCI-X (VREF = 1.0 V)	✓	–	–	–	✓	✓	–	–	–	–	–	✓
3.3 V PCI/PCI-X (VREF= 1.5 V)	✓	–	–	–	✓	–	–	–	–	✓	–	✓
GTL + (3.3 V)	✓	–	–	–	✓	✓	–	–	–	–	–	✓
GTL + (2.5 V)	–	✓	–	–	–	–	✓	–	–	–	–	–
HSTL Class I	–	–	–	✓	–	–	–	✓	–	–	–	–
SSTL2 Class I & II	–	✓	–	–	–	–	–	–	✓	–	✓	–
SSTL3 Class I & II	✓	–	–	–	✓	–	–	–	–	✓	–	✓
LVDS (VREF = 1.0 V)	–	✓	–	–	–	–	✓	–	–	–	✓	–
LVDS (VREF = 1.25 V)	–	✓	–	–	–	–	–	–	✓	–	✓	–
LVPECL (VREF = 1.0 V)	✓	–	–	–	✓	✓	–	–	–	–	–	✓
LVPECL (VREF = 1.5 V)	✓	–	–	–	✓	–	–	–	–	✓	–	✓

Notes:

1. *Note that GTL+ 2.5 V is not supported across the full military temperature range.*
2. *A "✓" indicates whether standards can be used within a bank at the same time.*
   Examples:
   a) LVTTL can be used with 3.3V PCI and GTL+ (3.3V), when V_{REF} = 1.0V (GTL+ requirement).
   b) LVTTL can be used with 3.3V PCI and SSTL3 Class I and II, when V_{REF} = 1.5V (SSTL3 requirement).

Note that two I/O standards are compatible if:

- Their VCCI values are identical.
- Their VREF standards are identical (if applicable).

For example, if LVTTL 3.3 V (VREF= 1.0 V) is used, then the other available (i.e. compatible) I/O standards in the same bank are LVTTL 3.3 V PCI/PCI-X, GTL+, and LVPECL.

Also note that when multiple I/O standards are used within a bank, the voltage tolerance will be limited to the minimum tolerance of all I/O standards used in the bank.

User I/O Naming Conventions

Due to the complex and flexible nature of the Axcelerator family's user I/Os, a naming scheme is used to show the details of the I/O. The naming scheme explains to which bank an I/O belongs, as well as the pairing and pin polarity for differential I/Os (Figure 2-7).

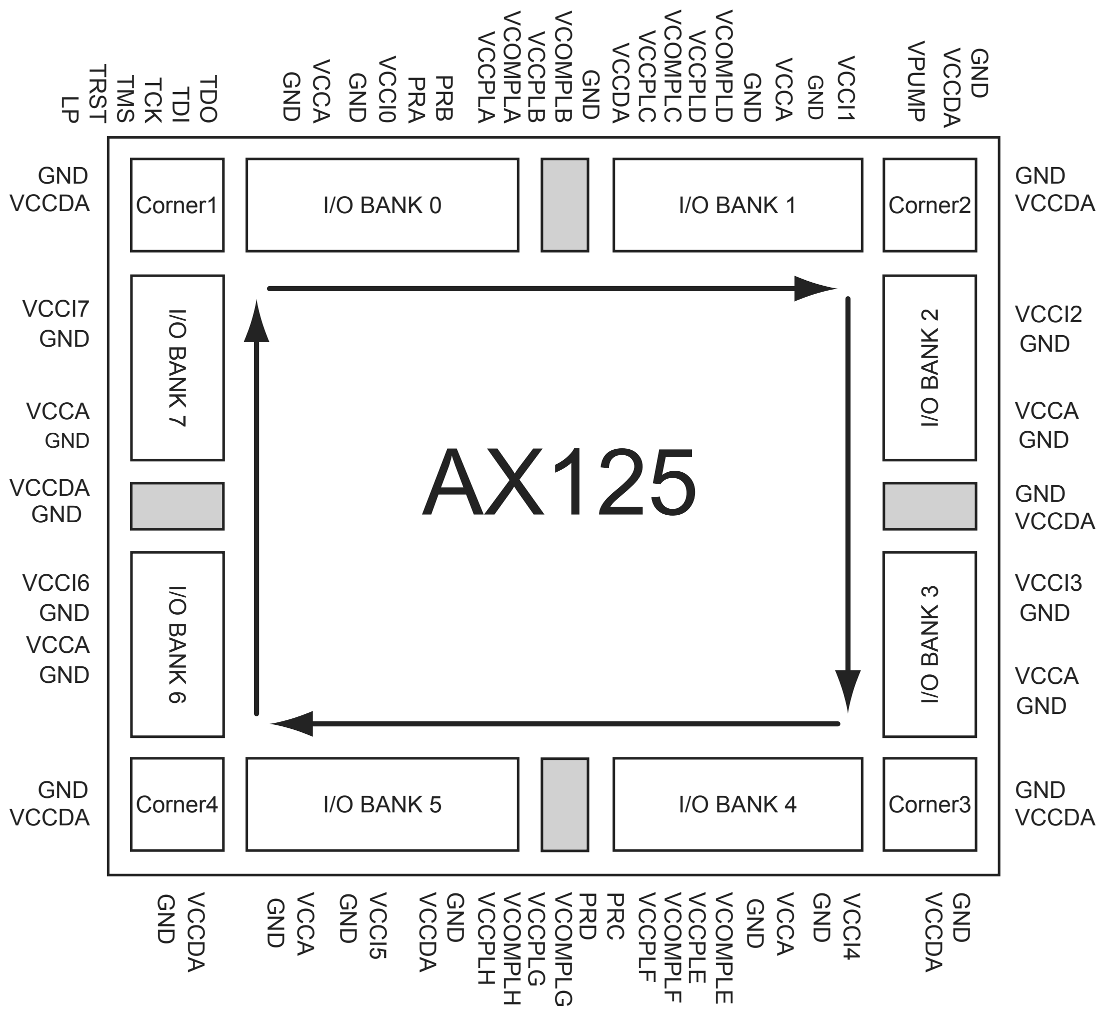
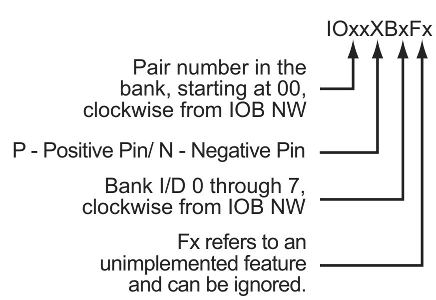


Figure 2-7 • **I/O Bank and Dedicated Pin Layout**



Examples:

IO12PB1F1 is the positive pin of the thirteenth pair of the first I/O bank (IOB NE). IO12PB1 combined with IO12NB1 form a differential pair.

For those I/Os that can be employed either as a user I/O or as a special function, the following nomenclature is used:

IOxxXBxFx/special_function_name

IOxxPB1Fx/xCLKx this pin can be configured as a clock input or as a user I/O.

Figure 2-8 • **General Naming Schemes**

Table 2-22 • 3.3 V LVTTL I/O Module
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C (continued)

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
LVTTL Output Drive Strength =3 (16 mA) / High Slew Rate								
t_{DP}	Input Buffer		1.68		1.92		2.26	ns
t_{PY}	Output Buffer		3.12		3.56		4.18	ns
t_{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		3.54		4.04		4.75	ns
t_{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		2.78		3.17		3.72	ns
t_{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		1.91		1.93		1.93	ns
t_{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		2.58		2.59		2.60	ns
t_{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t_{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

1.8 V LVCMOS

Low-Voltage Complementary Metal-Oxide Semiconductor for 1.8 V is an extension of the LVCMOS standard (JESD8-5) used for general-purpose 1.8 V applications. It uses a 3.3 V tolerant CMOS input buffer and a push-pull output buffer.

Table 2-26 **• DC Input and Output Levels**

VIL		VIH		VOL	VOH	IOL	IOH
Min., V	**Max., V**	**Min., V**	**Max., V**	**Max., V**	**Min., V**	**mA**	**mA**
–0.3	0.2 VCCI	0.7 VCCI	3.6	0.2	VCCI – 0.2	8 mA	–8 mA

AC Loadings

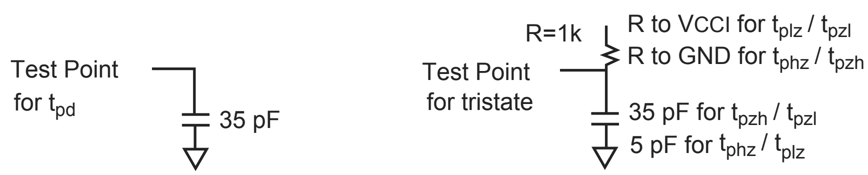


Figure 2-17 **• AC Test Loads**

Table 2-27 **• AC Waveforms, Measuring Points, and Capacitive Loads**

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ) (V)	C_{load} (pF)
0	1.8	0.5 VCCI	N/A	35

*Note: * Measuring Point = VTRIP*

Timing Characteristics

Table 2-32 • 1.5V LVCMOS I/O Module
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 1.4 V, TJ = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
LVCMOS15 (JESD8-11) I/O Module Timing								
t_{DP}	Input Buffer		3.59		4.09		4.81	ns
t_{PY}	Output Buffer		6.05		6.89		8.10	ns
t_{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		3.31		3.34		3.34	ns
t_{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		4.56		4.58		4.59	ns
t_{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		6.37		7.25		8.52	ns
t_{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		6.94		7.90		9.29	ns
t_{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t_{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

3.3 V PCI, 3.3 V PCI-X

Peripheral Component Interface for 3.3 V standard specifies support for both 33 MHz and 66 MHz PCI bus applications. It uses an LVTTL input buffer and a push-pull output buffer. The input and output buffers are 5 V tolerant with the aid of external components. Axcelerator 3.3 V PCI and 3.3 V PCI-X buffers are compliant with the PCI Local Bus Specification Rev. 2.1.

The PCI Compliance Specification requires the clamp diodes to be able to withstand for 11 ns, –3.5 V in undershoot, and 7.1 V in overshoot.

***Table 2-33* • DC Input and Output Levels**

	VIL		VIH		VOL	VOH	IOL	IOH
	Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA
PCI	–0.3	0.3 VCCI	0.5 VCCI	VCCI + 0.5	(per PCI specification)			
PCI-X	–0.5	0.35 VCCI	0.5 VCCI	VCCI + 0.5	(per PCI specification)			

AC Loadings

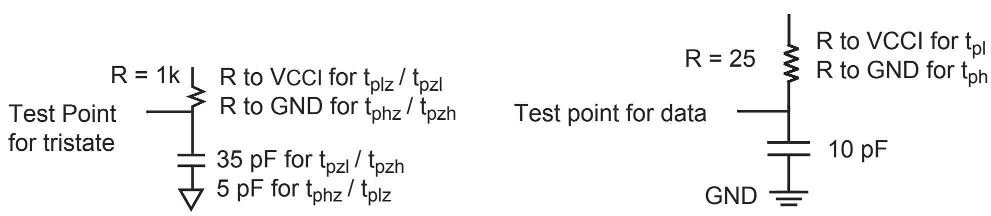


***Figure 2-18* • AC Test Loads**

***Table 2-34* • AC Waveforms, Measuring Points, and Capacitive Loads**

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ) (V)	C_{load} (pF)
(Per PCI Spec and PCI-X Spec)			N/A	10

*Note: * Measuring Point = VTRIP*

HSTL Class I

High-Speed Transceiver Logic is a general-purpose high-speed 1.5 V bus standard (EIA/JESD8-6). The Axcelerator devices support Class I. This requires a differential amplifier input buffer and a push-pull output buffer.

Table 2-41 **• DC Input and Output Levels**

VIL		VIH		VOL	VOH	IOL	IOH
Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA
-0.3	VREF – 0.1	VREF + 0.1	3.6	0.4	VCC – 0.4	8	-8

AC Loadings

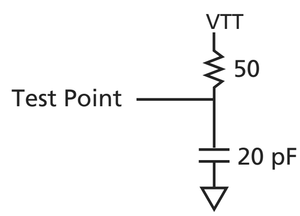


Figure 2-20 **• AC Test Loads**

Table 2-42 **• AC Waveforms, Measuring Points, and Capacitive Loads**

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ) (V)	C_{load} (pF)
VREF –0.5	VREF + 0.5	VREF	0.75	20

*Note: * Measuring Point = VTRIP*

Timing Characteristics

Table 2-43 **• 1.5 V HSTL Class I I/O Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 1.425 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Units
1.5 V HSTL Class I I/O Module Timing								
t_{DP}	Input Buffer		1.80		2.05		2.41	ns
t_{PY}	Output Buffer		4.90		5.58		6.56	ns
t_{ICLKQ}	Clock-to-Q for the I/O input register		0.67		0.77		0.90	ns
t_{OCLKQ}	Clock-to-Q for the I/O output register and the I/O enable register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

Buffer Module

Introduction

An additional resource inside each SuperCluster is the Buffer (B) module (Figure 1-4 on page 1-3). When a fanout constraint is applied to a design, the synthesis tool inserts buffers as needed. The buffer module has been added to the AX architecture to avoid logic duplication resulting from the hard fanout constraints. The router utilizes this logic resource to save area and reduce loading and delays on medium-to-high-fanout nets.

Timing Models and Waveforms

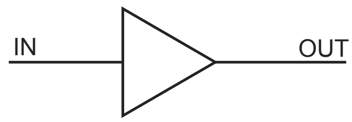


***Figure 2-33* • Buffer Module Timing Model**

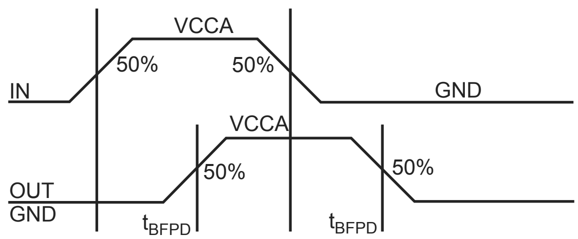


***Figure 2-34* • Buffer Module Waveform**

Timing Characteristics

***Table 2-64* • Buffer Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
Buffer Module Propagation Delays								
t_{BFPD}	Any input to output Y		0.12		0.14		0.16	ns

Implementation Example:

Figure 2-47 shows a complex clock distribution example. The reference clock (RefCLK) of PLLE is being sourced from non-clock signal pins (INBUF to PLLINT). The CLK1 output of PLLE is being fed to the RefCLK input of PLLF. The CLK2 output of PLLE is driving logic (via PLLOUT). In turn, this logic is driving the global resource CLKE. PLLF is driving both CLKF and CLKG global resources.

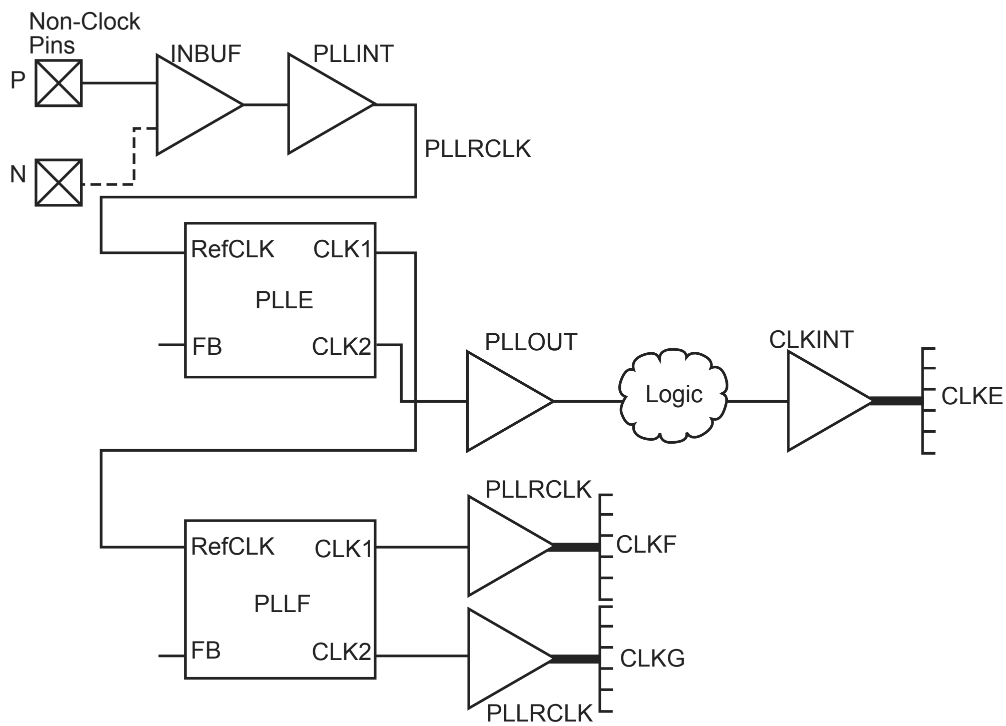


***Figure 2-47* • Complex Clock Distribution Example**

Figure 2-63 illustrates flag generation.

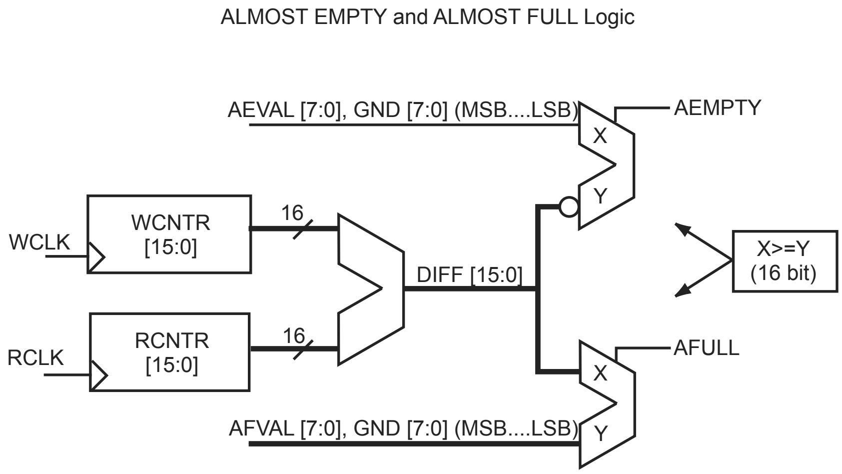


***Figure 2-63* • ALMOST-EMPTY and ALMOST-FULL Logic**

The Verilog codes for the flags are:

```
assign AF = (DIFF[15:0] >={AFVAL[7:0],8'b00000000})?1:0;
assign AE = ({AEVAL[7:0],8'b00000000}>=DIFF[15:0])?1:0;
```

The number of DIFF-bits active depends on the configuration depth and width (Table 2-95).

***Table 2-95* • Number of Available Configuration Bits**

Number of Blocks	Block DxW	Number of AEVAL/AFVAL Bits
1	1x1	4
2	1x2	4
2	2x1	5
4	1x4	4
4	2x2	5
4	4x1	6
8	1x8	4
8	2x4	5
8	4x2	6
8	8x1	7
16	1x16	4
16	2x8	5
16	4x4	6
16	8x2	7
16	16x1	8

The active-high CLR pin is used to reset the FIFO to the empty state, which sets FULL and AFULL low, and EMPTY and AEMPTY high.

Assuming that the EMPTY flag is not set, new data is read from the FIFO when REN is valid on the active edge of the clock. Write and read transfers are described with timing requirements in "Timing Characteristics" on page 2-100.

FG484	
AX1000 Function	Pin Number
Bank 0	
IO01NB0F0	E3
IO01PB0F0	D3
IO02NB0F0	E7
IO02PB0F0	E6
IO05NB0F0	D2
IO05PB0F0	E2
IO06NB0F0	C5
IO06PB0F0	C4
IO12NB0F1	D7
IO12PB0F1	D6
IO13NB0F1	B5
IO13PB0F1	B4
IO14NB0F1	E9
IO14PB0F1	E8
IO15NB0F1	C7
IO15PB0F1	C6
IO16NB0F1	A5
IO16PB0F1	A4
IO17NB0F1	B7
IO17PB0F1	B6
IO18NB0F1	A7
IO18PB0F1	A6
IO19NB0F1	C9
IO19PB0F1	C8
IO20NB0F1	D9
IO20PB0F1	D8
IO21NB0F1	B9
IO21PB0F1	B8
IO22NB0F2	A9
IO22PB0F2	A8
IO23NB0F2	B10
IO23PB0F2	A10
IO26NB0F2	A14
IO26PB0F2	A13

FG484	
AX1000 Function	Pin Number
IO29NB0F2	B12
IO29PB0F2	B11
IO30NB0F2/HCLKAN	E11
IO30PB0F2/HCLKAP	E10
IO31NB0F2/HCLKBN	D12
IO31PB0F2/HCLKBP	D11
Bank 1	
IO32NB1F3/HCLKCN	F13
IO32PB1F3/HCLKCP	F12
IO33NB1F3/HCLKDN	E14
IO33PB1F3/HCLKDP	E13
IO34NB1F3	C13
IO34PB1F3	C12
IO37NB1F3	B14
IO37PB1F3	B13
IO38NB1F3	A16
IO38PB1F3	A15
IO40NB1F3	C15
IO42NB1F4	A18
IO42PB1F4	A17
IO43NB1F4	B16
IO43PB1F4	B15
IO44NB1F4	B18
IO44PB1F4	B17
IO45NB1F4	B19
IO45PB1F4	A19
IO46NB1F4	C19
IO46PB1F4	C18
IO48NB1F4	F15
IO48PB1F4	F14
IO49NB1F4	D16
IO49PB1F4	D15
IO50NB1F4	C17
IO50PB1F4	C16
IO51NB1F4	E22

FG484	
AX1000 Function	Pin Number
IO51PB1F4	D22
IO52NB1F4	E16
IO52PB1F4	E15
IO57NB1F5	E21
IO57PB1F5	D21
IO60NB1F5	G16
IO60PB1F5	G15
IO61NB1F5	D18
IO61PB1F5	E17
IO63NB1F5	E20
IO63PB1F5	D20
Bank 2	
IO64NB2F6	F18
IO64PB2F6	F17
IO67NB2F6	F19
IO67PB2F6	E19
IO68NB2F6	J16
IO68PB2F6	H16
IO70NB2F6	J17
IO70PB2F6	H17
IO74NB2F7	J18
IO74PB2F7	H18
IO75NB2F7	G20
IO75PB2F7	F20
IO79NB2F7	H19
IO79PB2F7	G19
IO80NB2F7	L16
IO80PB2F7	K16
IO84NB2F7	L17
IO84PB2F7	K17
IO85NB2F8	G21
IO85PB2F8	F21
IO86NB2F8	G22
IO86PB2F8	F22
IO87NB2F8	J20

FG676	
AX500 Function	Pin Number
IO51NB2F4	L20
IO51PB2F4	L21
IO52NB2F5	K26
IO52PB2F5	J26
IO53NB2F5	L23
IO53PB2F5	L22
IO54NB2F5	L24
IO54PB2F5	K24
IO55NB2F5	M20
IO55PB2F5	M21
IO56NB2F5	L26
IO56PB2F5	L25
IO57NB2F5	M23
IO57PB2F5	M22
IO58NB2F5	M26
IO58PB2F5	M25
IO59NB2F5	N22
IO59PB2F5	N23
IO60NB2F5	N24
IO60PB2F5	M24
IO61NB2F5	N20
IO61PB2F5	N21
IO62NB2F5	P25
IO62PB2F5	N25
Bank 3	
IO63NB3F6	T26
IO63PB3F6	R26
IO64NB3F6	R24
IO64PB3F6	P24
IO65NB3F6	P20
IO65PB3F6	P21
IO66NB3F6	T25
IO66PB3F6	R25
IO67NB3F6	T23
IO67PB3F6	R23

FG676	
AX500 Function	Pin Number
IO68NB3F6	V26
IO68PB3F6	U26
IO69NB3F6	V25
IO69PB3F6	U25
IO70NB3F6	Y25
IO70PB3F6	W25
IO71NB3F6	W24
IO71PB3F6	V24
IO72NB3F6	V23
IO72PB3F6	U23
IO73NB3F6	T21
IO73PB3F6	T20
IO74NB3F7	AA26
IO74PB3F7	Y26
IO75NB3F7	AA24
IO75PB3F7	Y24
IO76NB3F7	Y23
IO76PB3F7	W23
IO77NB3F7	V21
IO77PB3F7	U21
IO78NB3F7	AB25
IO78PB3F7	AA25
IO79NB3F7	AC26
IO79PB3F7	AB26
IO80NB3F7	AC24
IO80PB3F7	AB24
IO81NB3F7	AB23
IO81PB3F7	AA23
IO82NB3F7	AA22
IO82PB3F7	Y22
IO83NB3F7	AE26
IO83PB3F7	AD26
Bank 4	
IO84NB4F8	AB21
IO84PB4F8	AA21

FG676	
AX500 Function	Pin Number
IO85NB4F8	AE23
IO85PB4F8	AE24
IO86NB4F8	AC21
IO86PB4F8	AC22
IO87NB4F8	AF22
IO87PB4F8	AF23
IO88NB4F8	AD22
IO88PB4F8	AD23
IO89NB4F8	AC19
IO89PB4F8	AC20
IO90NB4F8	AE21
IO90PB4F8	AE22
IO91NB4F8	AA17
IO91PB4F8	AA18
IO92NB4F8	AD20
IO92PB4F8	AD21
IO93NB4F8	AF20
IO93PB4F8	AF21
IO94NB4F9	AE19
IO94PB4F9	AE20
IO95NB4F9	AC17
IO95PB4F9	AC18
IO96NB4F9	AD18
IO96PB4F9	AD19
IO97NB4F9	AA16
IO97PB4F9	Y16
IO98NB4F9	AE17
IO98PB4F9	AE18
IO99NB4F9	AC16
IO99PB4F9	AB16
IO100NB4F9	AF17
IO100PB4F9	AF18
IO101NB4F9	AA15
IO101PB4F9	Y15
IO102NB4F9	AC15

FG896	
AX1000 Function	Pin Number
VCCIB2	L22
VCCIB2	M21
VCCIB2	M22
VCCIB2	N21
VCCIB2	P21
VCCIB2	R21
VCCIB3	AA22
VCCIB3	AH29
VCCIB3	AH30
VCCIB3	T21
VCCIB3	U21
VCCIB3	V21
VCCIB3	W21
VCCIB3	W22
VCCIB3	Y21
VCCIB3	Y22
VCCIB4	AA16
VCCIB4	AA17
VCCIB4	AA18
VCCIB4	AA19
VCCIB4	AA20
VCCIB4	AB19
VCCIB4	AB20
VCCIB4	AB21
VCCIB4	AJ28
VCCIB4	AK28
VCCIB5	AA11
VCCIB5	AA12
VCCIB5	AA13
VCCIB5	AA14
VCCIB5	AA15
VCCIB5	AB10
VCCIB5	AB11
VCCIB5	AB12
VCCIB5	AJ3

FG896	
AX1000 Function	Pin Number
VCCIB5	AK3
VCCIB6	AA9
VCCIB6	AH1
VCCIB6	AH2
VCCIB6	T10
VCCIB6	U10
VCCIB6	V10
VCCIB6	W10
VCCIB6	W9
VCCIB6	Y10
VCCIB6	Y9
VCCIB7	C1
VCCIB7	C2
VCCIB7	K9
VCCIB7	L10
VCCIB7	L9
VCCIB7	M10
VCCIB7	M9
VCCIB7	N10
VCCIB7	P10
VCCIB7	R10
VCOMPLA	F14
VCOMPLB	J15
VCOMPLC	F17
VCOMPLD	H16
VCOMPLE	AF17
VCOMPLF	AD16
VCOMPLG	AF14
VCOMPLH	AB15
VPUMP	G24

CQ208	
AX500 Function	Pin Number
IO150PB7F14	19
IO152NB7F14	16
IO152PB7F14	17
IO161NB7F15	12
IO161PB7F15	13
IO163NB7F15	10
IO163PB7F15	11
IO165PB7F15	7
IO166NB7F15	5
IO166PB7F15	6
IO167NB7F15	3
IO167PB7F15	4
Dedicated I/O	
VCCDA	1
GND	9
GND	15
GND	21
GND	32
GND	39
GND	46
GND	51
GND	59
GND	65
GND	69
GND	90
GND	94
GND	99
GND	104
GND	113
GND	119
GND	125
GND	136
GND	143
GND	150
GND	155
GND	164
GND	169

CQ208	
AX500 Function	Pin Number
GND	173
GND	194
GND	196
GND	201
GND/LP	208
PRA	184
PRB	183
PRC	80
PRD	79
TCK	205
TDI	204
TDO	203
TMS	206
TRST	207
VCCA	2
VCCA	14
VCCA	38
VCCA	52
VCCA	64
VCCA	93
VCCA	118
VCCA	142
VCCA	156
VCCA	168
VCCA	195
VCCDA	26
VCCDA	53
VCCDA	63
VCCDA	78
VCCDA	95
VCCDA	105
VCCDA	130
VCCDA	157
VCCDA	167
VCCDA	182
VCCDA	202
VCCIB0	193

CQ208	
AX500 Function	Pin Number
VCCIB0	200
VCCIB1	163
VCCIB1	172
VCCIB2	135
VCCIB2	149
VCCIB3	112
VCCIB3	124
VCCIB4	89
VCCIB4	98
VCCIB5	58
VCCIB5	68
VCCIB6	31
VCCIB6	45
VCCIB7	8
VCCIB7	20
VCCPLA	189
VCCPLB	187
VCCPLC	178
VCCPLD	176
VCCPLE	85
VCCPLF	83
VCCPLG	74
VCCPLH	72
VCOMPLA	190
VCOMPLB	188
VCOMPLC	179
VCOMPLD	177
VCOMPLE	86
VCOMPLF	84
VCOMPLG	75
VCOMPLH	73
VPUMP	158

CQ352	
AX1000 Function	Pin Number
VCCDA	346
VCCIB0	321
VCCIB0	333
VCCIB0	344
VCCIB1	273
VCCIB1	285
VCCIB1	297
VCCIB2	227
VCCIB2	239
VCCIB2	245
VCCIB2	257
VCCIB3	185
VCCIB3	197
VCCIB3	203
VCCIB3	215
VCCIB4	144
VCCIB4	156
VCCIB4	168
VCCIB5	96
VCCIB5	108
VCCIB5	120
VCCIB6	50
VCCIB6	62
VCCIB6	68
VCCIB6	80
VCCIB7	8
VCCIB7	20
VCCIB7	26
VCCIB7	38
VCCPLA	317
VCCPLB	315
VCCPLC	303
VCCPLD	301
VCCPLE	140
VCCPLF	138

CQ352	
AX1000 Function	Pin Number
VCCPLG	126
VCCPLH	124
VCOMPLA	318
VCOMPLB	316
VCOMPLC	304
VCOMPLD	302
VCOMPLE	141
VCOMPLF	139
VCOMPLG	127
VCOMPLH	125
VPUMP	267

CG624	
AX1000 Function	Pin Number
IO63PB1F5	G18
Bank 2	
IO64NB2F6	M17
IO64PB2F6	G22
IO65NB2F6	J21
IO65PB2F6	J20
IO66NB2F6	L23
IO66PB2F6	K20
IO67NB2F6	F23
IO67PB2F6	E23
IO68NB2F6	L18
IO68PB2F6	K18
IO70NB2F6	E24
IO70PB2F6	D24
IO71NB2F6	H23
IO71PB2F6	G23
IO72NB2F6	L19
IO72PB2F6	K19
IO74NB2F7	J22
IO74PB2F7	H22
IO75NB2F7	N23
IO75PB2F7	M23
IO76NB2F7	N17
IO76PB2F7	N16
IO77NB2F7	L22
IO77PB2F7	K22
IO78NB2F7	M19
IO78PB2F7	M18
IO79NB2F7	N19
IO79PB2F7	N18
IO80NB2F7	L21
IO80PB2F7	L20
IO82NB2F7	P18
IO82PB2F7	P17
IO83NB2F7	N22
IO83PB2F7	M22

CG624	
AX1000 Function	Pin Number
IO84NB2F7	M20
IO84PB2F7	M21
IO86NB2F8	E25
IO86PB2F8	D25
IO87NB2F8	L24
IO87PB2F8	K24
IO88NB2F8	G24
IO88PB2F8	F24
IO89NB2F8	J25
IO90NB2F8	G25
IO90PB2F8	F25
IO91NB2F8	L25
IO91PB2F8	K25
IO92NB2F8	J24
IO92PB2F8	H24
IO93PB2F8	J23
IO94NB2F8	N24
IO94PB2F8	M24
IO95NB2F8	N25
IO95PB2F8	M25
Bank 3	
IO96NB3F9	T18
IO96PB3F9	R18
IO97NB3F9	N20
IO97PB3F9	P24
IO98NB3F9	P20
IO98PB3F9	P19
IO99NB3F9	P21
IO100NB3F9	T22
IO100PB3F9	W24
IO101NB3F9	R22
IO101PB3F9	P22
IO102NB3F9	U19
IO102PB3F9	T19
IO104NB3F9	V20
IO104PB3F9	U20

CG624	
AX1000 Function	Pin Number
IO105NB3F9	R23
IO105PB3F9	P23
IO106NB3F9	R19
IO106PB3F9	R20
IO107NB3F10	AB24
IO108NB3F10	R25
IO108PB3F10	P25
IO109NB3F10	U25
IO109PB3F10	T25
IO110NB3F10	U24
IO110PB3F10	U23
IO112NB3F10	T24
IO112PB3F10	R24
IO113NB3F10	Y25
IO113PB3F10	W25
IO114NB3F10	V23
IO114PB3F10	V24
IO116NB3F10	AA24
IO116PB3F10	Y24
IO117NB3F10	AB25
IO117PB3F10	AA25
IO118NB3F11	T20
IO118PB3F11	R21
IO120NB3F11	W22
IO120PB3F11	W23
IO122NB3F11	V22
IO122PB3F11	U22
IO124NB3F11	Y23
IO124PB3F11	AA23
IO126NB3F11	V21
IO126PB3F11	U21
IO128NB3F11	Y22
IO128PB3F11	Y21
Bank 4	
IO129NB4F12	W20
IO129PB4F12	Y20

CG624	
AX1000 Function	Pin Number
IO131NB4F12	V19
IO131PB4F12	W19
IO133NB4F12	Y18
IO133PB4F12	Y19
IO135NB4F12	W18
IO135PB4F12	V18
IO137NB4F12	Y17
IO137PB4F12	AA17
IO138NB4F12	AB19
IO138PB4F12	AB18
IO139NB4F13	AA19
IO139PB4F13	U18
IO140NB4F13	AC20
IO140PB4F13	AC21
IO141NB4F13	AD17
IO141PB4F13	AD18
IO142NB4F13	AD21
IO142PB4F13	AD22
IO143NB4F13	AB17
IO143PB4F13	AC17
IO144PB4F13	AE22
IO145NB4F13	AE15
IO145PB4F13	AE16
IO146NB4F13	AD19
IO146PB4F13	AD20
IO147NB4F13	AD15
IO147PB4F13	AD16
IO148PB4F13	AE21
IO149NB4F13	AD14
IO149PB4F13	AC14
IO150NB4F13	AE19
IO150PB4F13	AE20
IO151NB4F13	V17
IO151PB4F13	W17
IO152NB4F14	AB16
IO152PB4F14	W16

CG624	
AX1000 Function	Pin Number
IO153NB4F14	Y15
IO153PB4F14	Y16
IO155NB4F14	V15
IO155PB4F14	V16
IO156NB4F14	AB14
IO156PB4F14	AB15
IO157NB4F14	AE14
IO157PB4F14	AC18
IO158NB4F14	AC15
IO158PB4F14	AC19
IO159NB4F14/CLKEN	W14
IO159PB4F14/CLKEP	W15
IO160NB4F14/CLKFN	AC13
IO160PB4F14/CLKFP	AD13
Bank 5	
IO161NB5F15/CLKGN	W13
IO161PB5F15/CLKGP	Y13
IO162NB5F15/CLKHN	AC12
IO162PB5F15/CLKHP	AD12
IO163NB5F15	V9
IO163PB5F15	V10
IO164NB5F15	V11
IO164PB5F15	T13
IO165NB5F15	U13
IO165PB5F15	V13
IO167NB5F15	W11
IO167PB5F15	W12
IO168NB5F15	AB6
IO168PB5F15	AA6
IO169NB5F15	V8
IO169PB5F15	V7
IO171NB5F16	W8
IO171PB5F16	W9
IO172NB5F16	AB8
IO172PB5F16	AC8
IO173NB5F16	AA11

CG624	
AX1000 Function	Pin Number
IO173PB5F16	Y11
IO174NB5F16	AB10
IO174PB5F16	AB11
IO175NB5F16	AC9
IO175PB5F16	AE9
IO177NB5F16	AA8
IO177PB5F16	Y8
IO178NB5F16	Y6
IO178PB5F16	W6
IO179NB5F16	Y10
IO179PB5F16	W10
IO180NB5F16	Y7
IO180PB5F16	W7
IO181NB5F17	AD9
IO181PB5F17	AD10
IO182NB5F17	AE10
IO182PB5F17	AE11
IO183NB5F17	AD7
IO183PB5F17	AD8
IO184NB5F17	AB9
IO185NB5F17	AE6
IO185PB5F17	AE7
IO186NB5F17	AE4
IO186PB5F17	AE5
IO187NB5F17	AA9
IO187PB5F17	Y9
IO188NB5F17	U8
IO189NB5F17	AD5
IO189PB5F17	AD6
IO191NB5F17	AC5
IO191PB5F17	AC6
IO192NB5F17	AB7
IO192PB5F17	AC7
Bank 6	
IO193NB6F18	U6
IO193PB6F18	U5

Datasheet Categories

Categories

In order to provide the latest information to designers, some datasheet parameters are published before data has been fully characterized from silicon devices. The data provided for a given device, as highlighted in the "Axcelerator Family Device Status" table on page iii, is designated as either "Product Brief," "Advance," "Preliminary," or "Production." The definitions of these categories are as follows:

Product Brief

The product brief is a summarized version of a datasheet (advance or production) and contains general product information. This document gives an overview of specific device and family information.

Advance

This version contains initial estimated information based on simulation, other products, devices, or speed grades. This information can be used as estimates, but not for production. This label only applies to the DC and Switching Characteristics chapter of the datasheet and will only be used when the data has not been fully characterized.

Preliminary

The datasheet contains information based on simulation and/or initial characterization. The information is believed to be correct, but changes are possible.

Production

This version contains information that is considered to be final.

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